What is claims is:

1.   A method for manufacturing the semiconductor device which includes a package having:

a mounting region for mounting at least one semiconductor element;

a first region containing said mounting region and substantially sharing point symmetry with said mounting region, the width of the portions of said first region not including said mounting region being substantially uniform; and

a second region provided at a perimeter edge of said first region and not substantially sharing point symmetry with said mounting region,

said method comprising the steps of:

mounting said semiconductor element on the mounting region by means of a flip chip coding;

supplying under-fill resin to said second region; and

causing said under-fill resin in said second region to move to said first region so that the gap between said semiconductor element and said mounting region is filled with the resin.

2.   A method for manufacturing a semiconductor device which includes a package having:

a mounting region for mounting at least one semiconductor element;

a first region containing said mounting region and substantially sharing point symmetry with said mounting region, the width of the portions of said first region not including said mounting region being substantially uniform; and

a second region provided at a perimeter edge of said first region and not substantially sharing point symmetry with said mounting region,

said method comprising the steps of:

arranging first bonding pads in said first region;

connecting first and second lead wires derived from said semiconductor element respectively to said first and second bonding pads.